

SOT751-2

plastic low profile fine-pitch ball grid array package; 80 balls;
body 7 x 7 x 0.9 mm

8 February 2016

Package information

1. Package summary

| | |
|---------------------------------------|--|
| Terminal position code | B (bottom) |
| Package type descriptive code | LFBGA80 |
| Package type industry code | LFBGA80 |
| Package style descriptive code | LFBGA (low profile fine-pitch ball grid array) |
| Package style suffix code | NA (not applicable) |
| Package body material type | P (plastic) |
| Mounting method type | S (surface mount) |
| Issue date | 16-9-2003 |

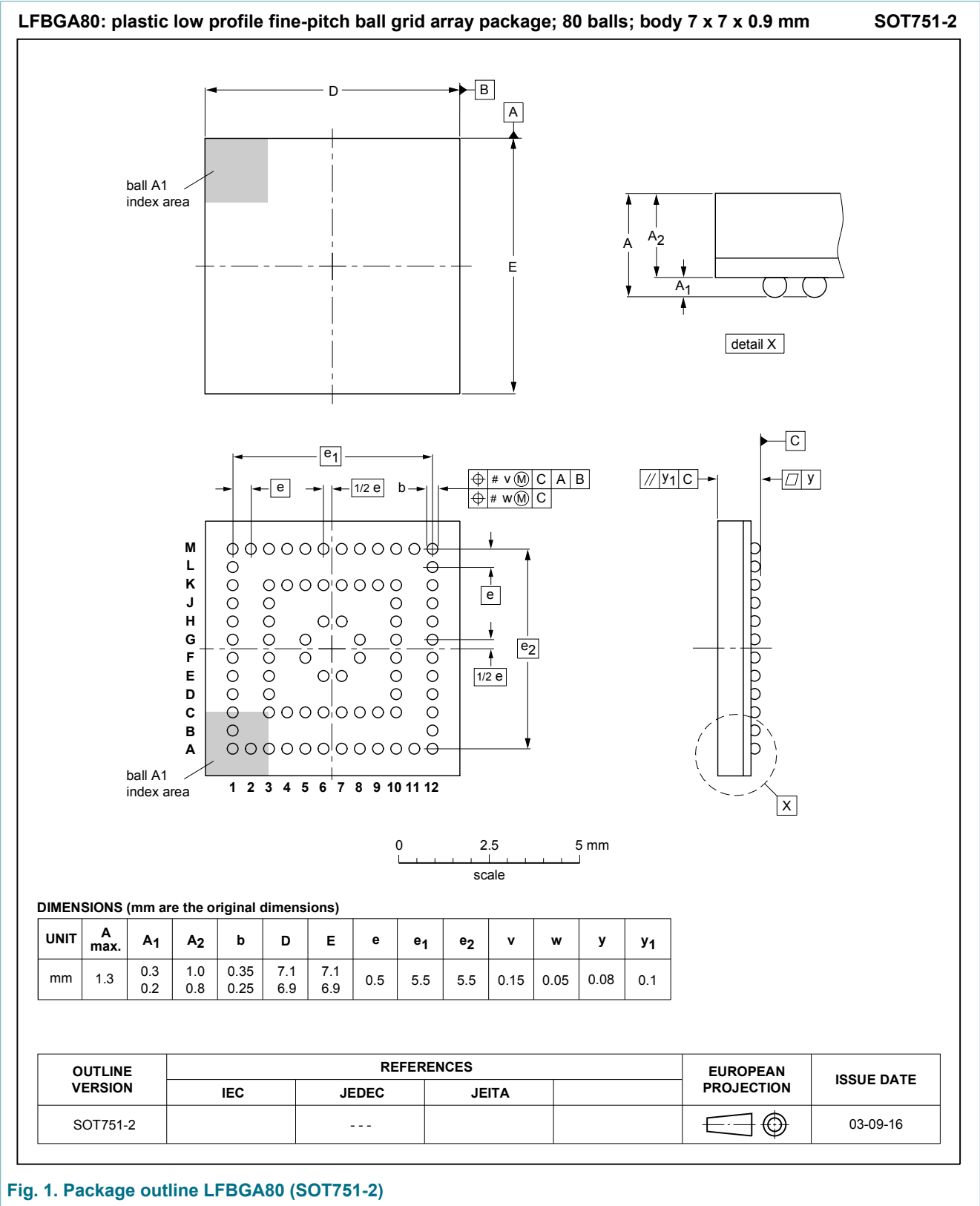
Table 1. Package summary

| Symbol | Parameter | | Min | Typ | Nom | Max | Unit |
|----------------|--------------------------------|--|-------|-----|-----|-----|------|
| D | package length | | 6.9 | - | 7 | 7.1 | mm |
| E | package width | | 6.9 | - | 7 | 7.1 | mm |
| A | seated height | | [tbd] | - | 1.3 | 1.3 | mm |
| A ₂ | package height | | 0.8 | - | 0.9 | 1 | mm |
| n ₂ | actual quantity of termination | | - | - | 80 | - | |



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2. Package outline



3. Soldering

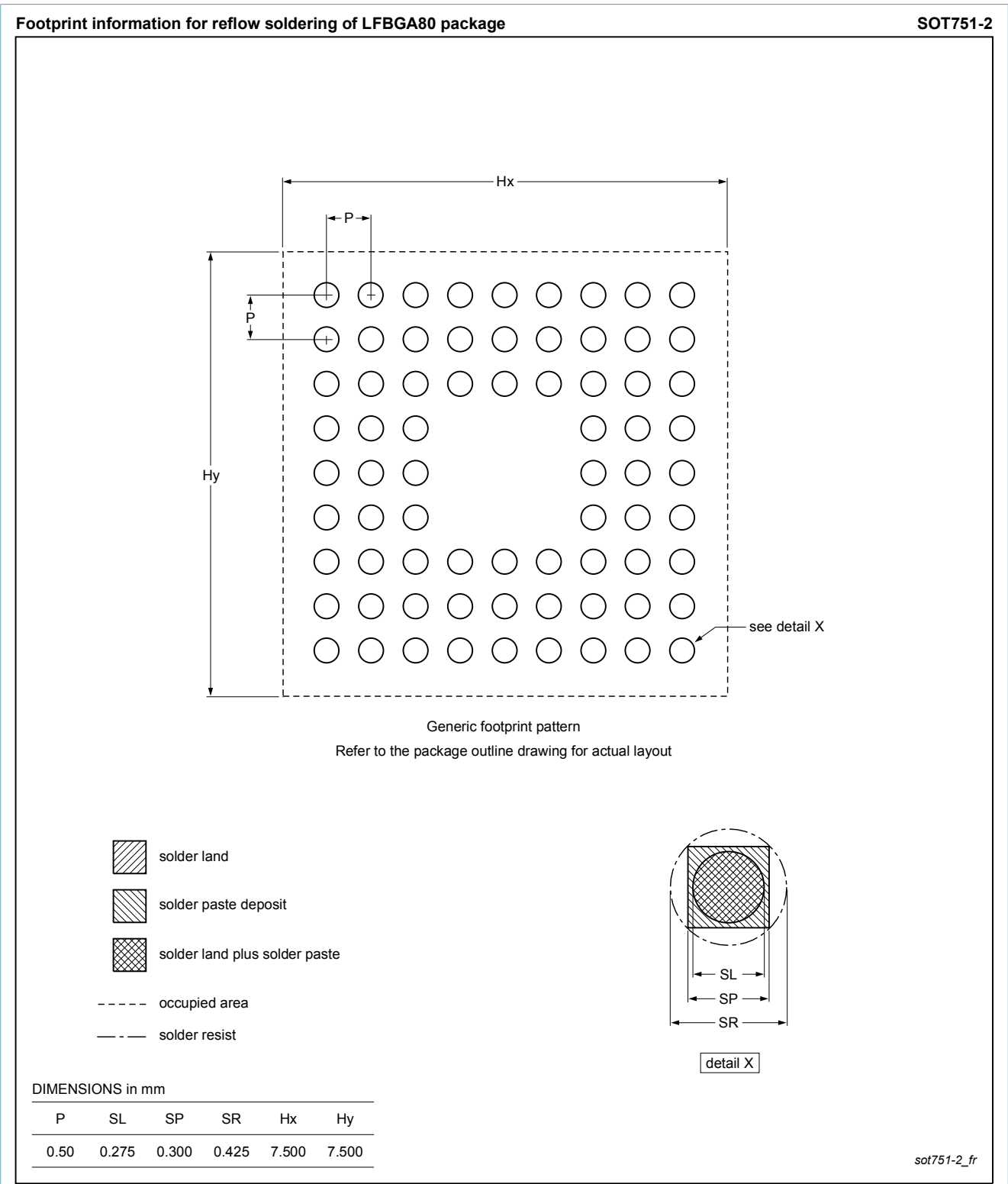


Fig. 2. Reflow soldering footprint for LFBGA80 (SOT751-2)

4. Legal information

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